

徐万劲 北京 北京大学物理学院 100871

摘要: 近年来磁控溅射技术的应用日趋广泛, 在工业生产和科学研究领域发挥巨大作用。随着对具有各种新型功能的薄膜需求的增加, 相应的磁控溅射技术也获得进一步的发展。本文将介绍磁控溅射技术的发展, 以及闭合磁场非平衡溅射、高速率溅射及自溅射、中频及脉冲溅射等各种新技术及特点, 阐述磁控溅射技术在电子、光学、表面功能薄膜、薄膜发光材料等许多方面的应用。

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Recent developments and applications in magnetron sputtering

100871

Abstract: Magnetron sputtering is a widely used method for thin film deposition in recent years, which makes a great impact on the industrial production and scientific research. Magnetron technology is continuously developing because new advanced films with specific functional properties are needed. The paper will describe the development of magnetron technology and novel technologies such as closed field unbalanced magnetron sputtering, High rate magnetron sputtering, sustained self sputtering, AC or medium frequency sputtering and pulsed sputtering. The application of magnetron sputtering in electronics, optics, surface engineering and electroluminescent component will be shown.

Key words:

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